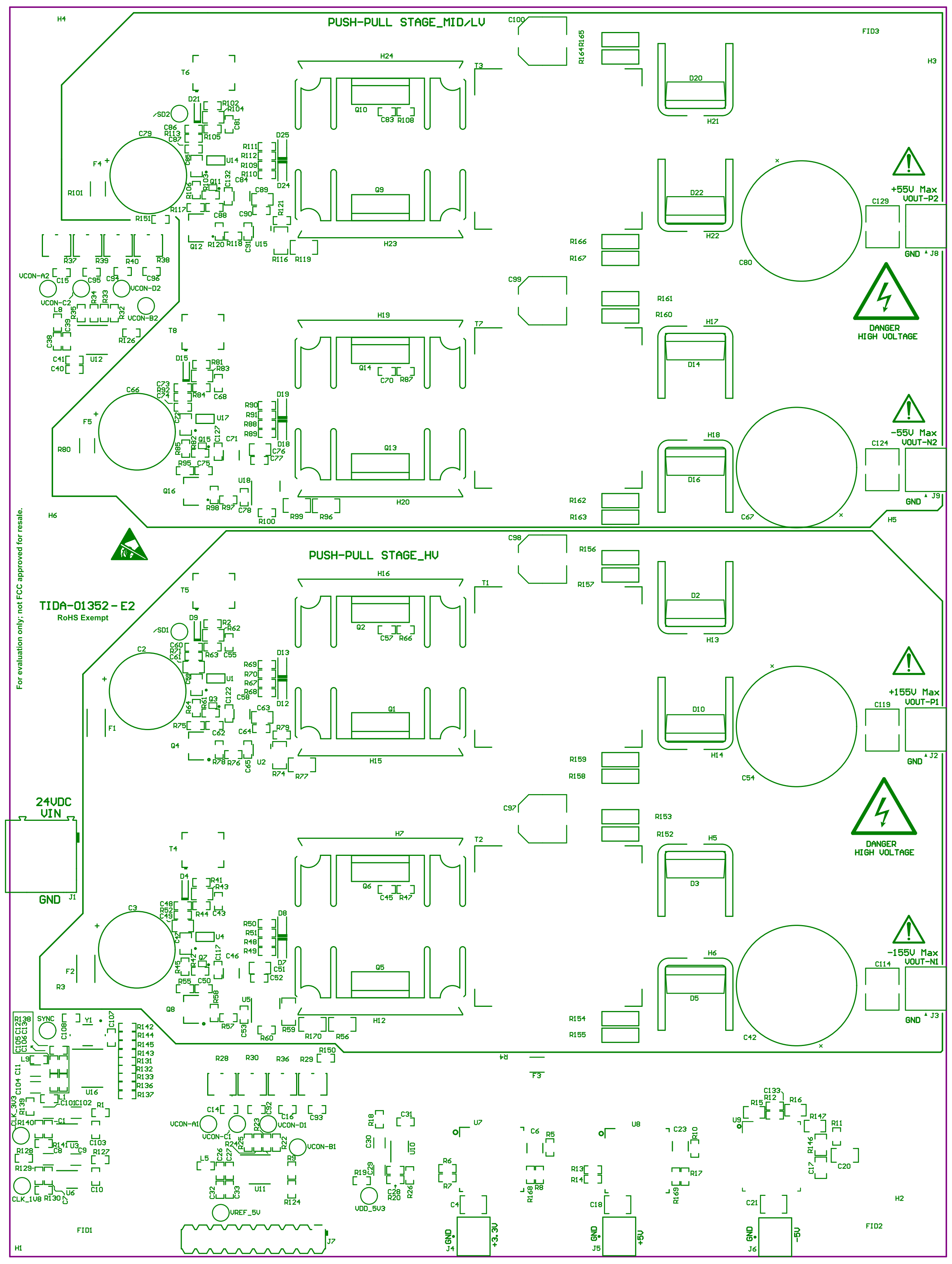
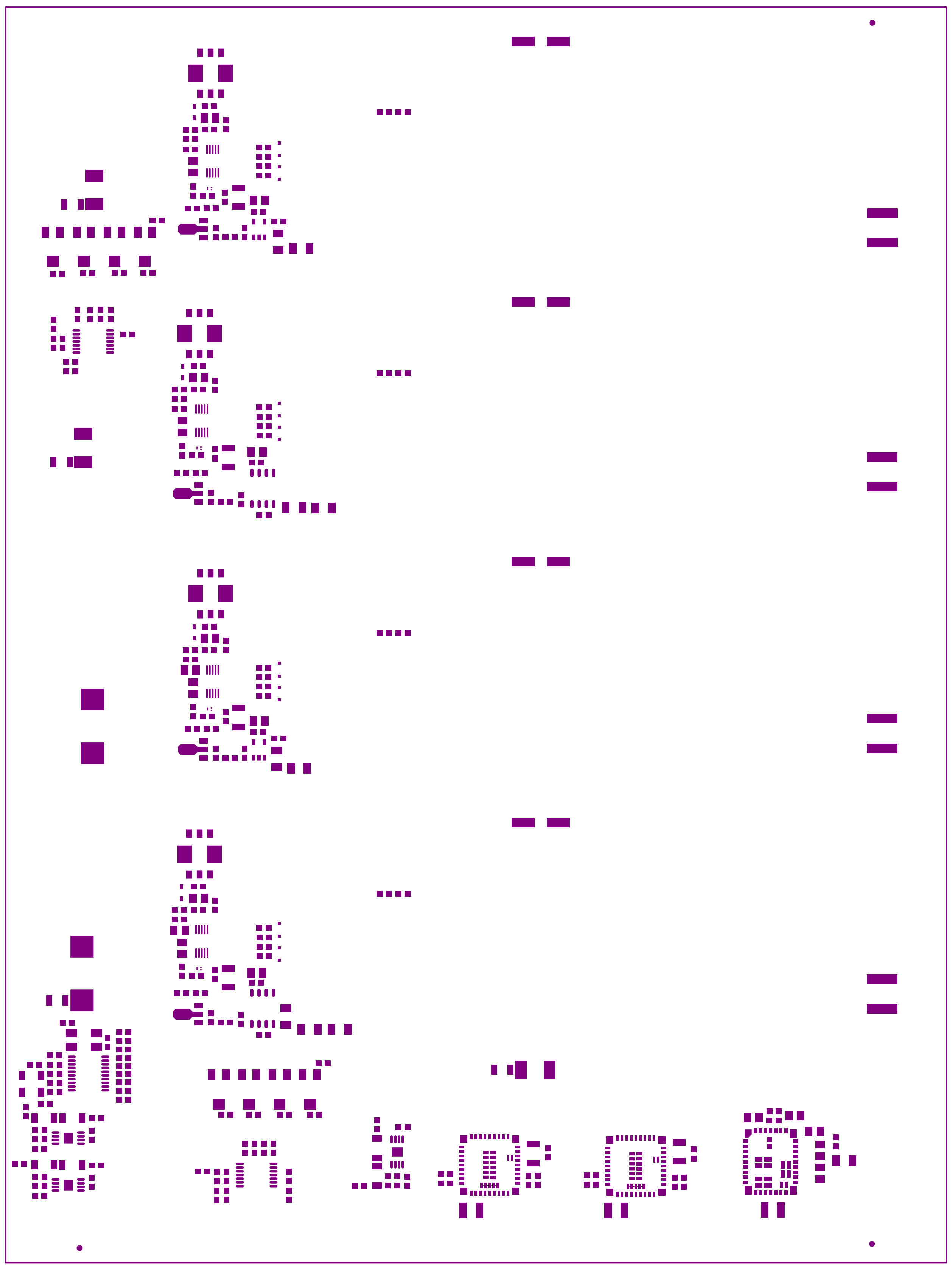
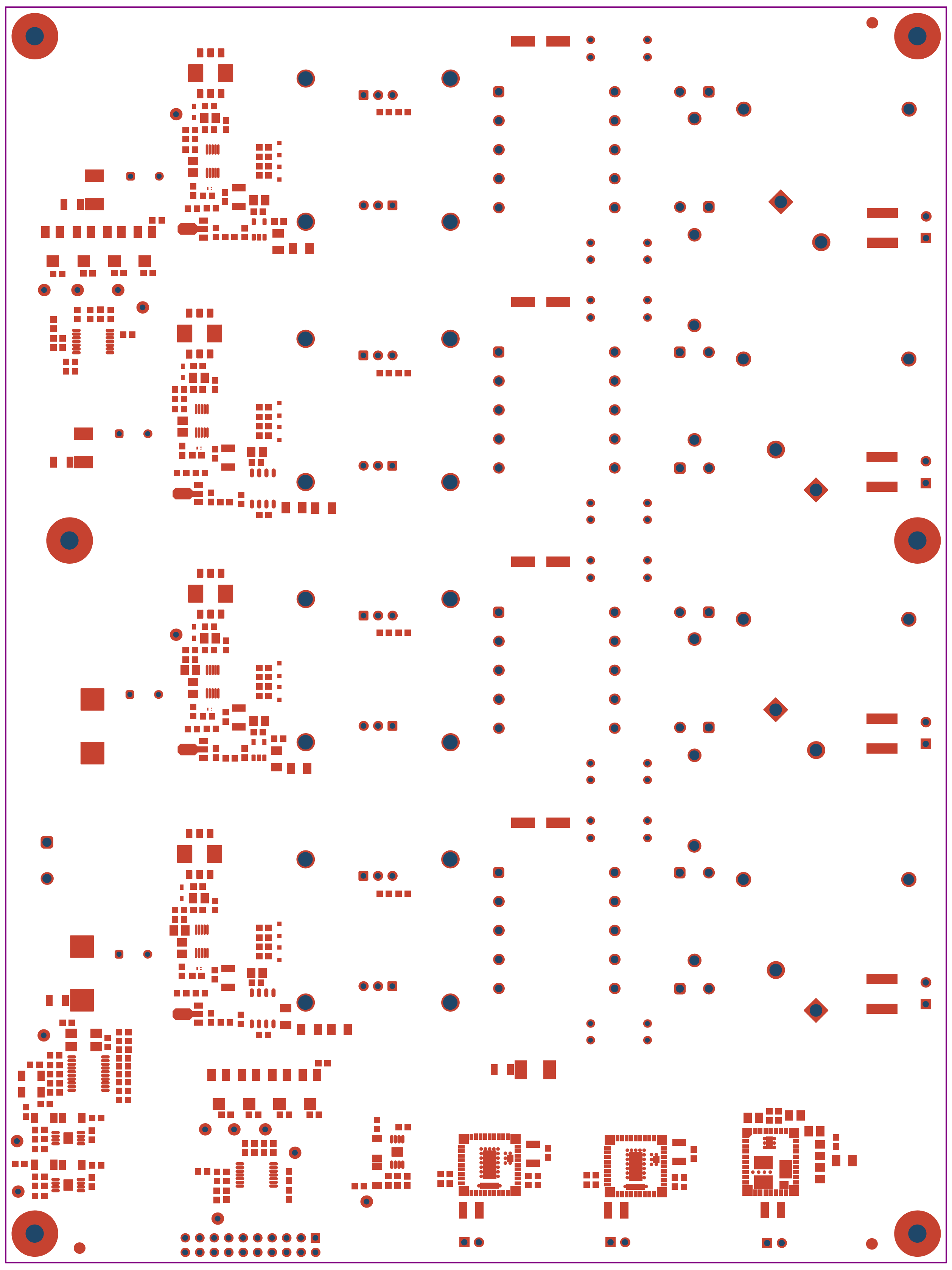


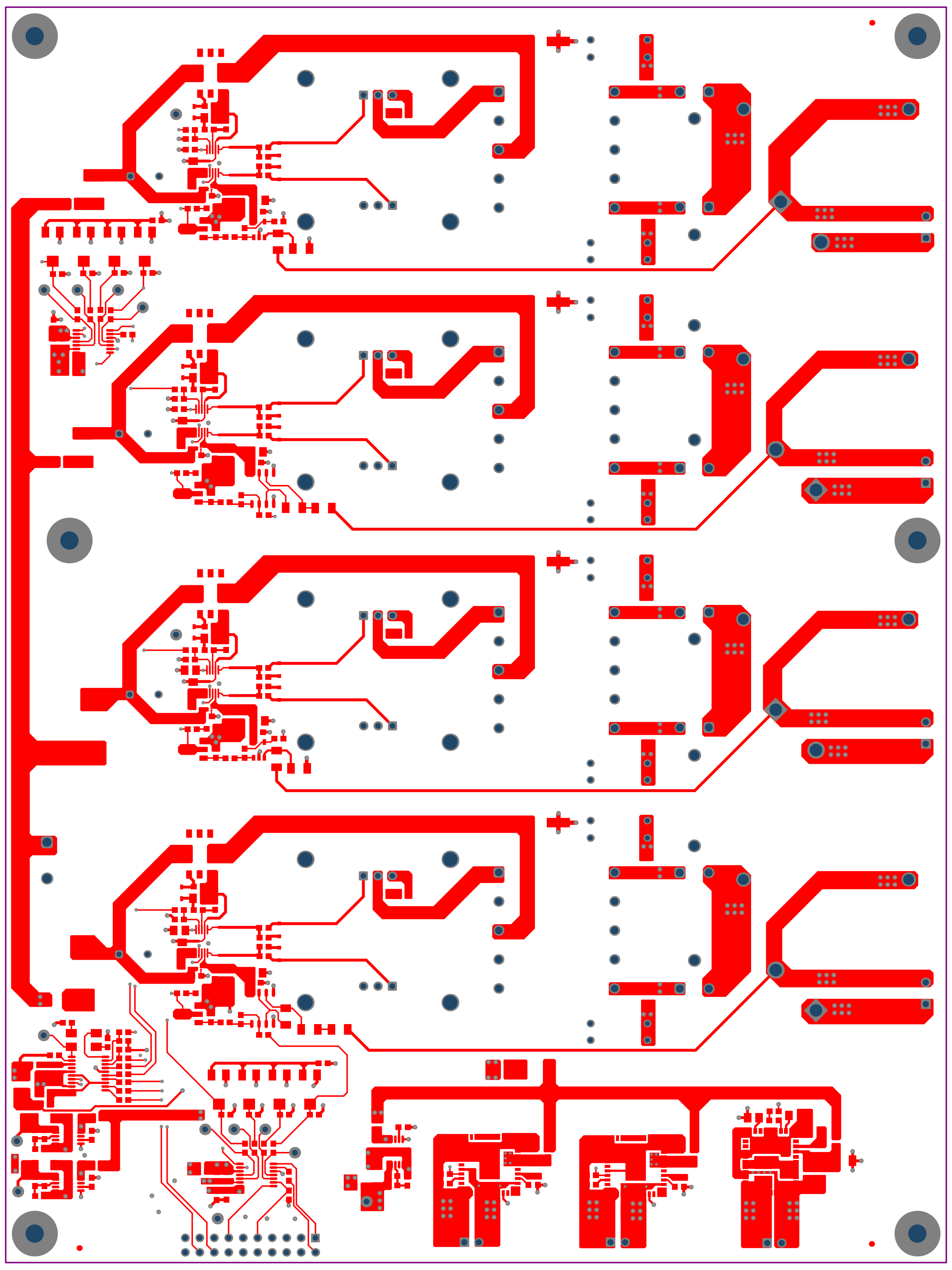
ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: TIDA-01352
REV: E2
SVN REV: Not In VersionControl
LAYER NAME = Top Overlay
TID #: TIDA-01352
PLOT NAME = Top Overlay
GENERATED : 19-06-2017 14:45:39
TEXAS INSTRUMENTS



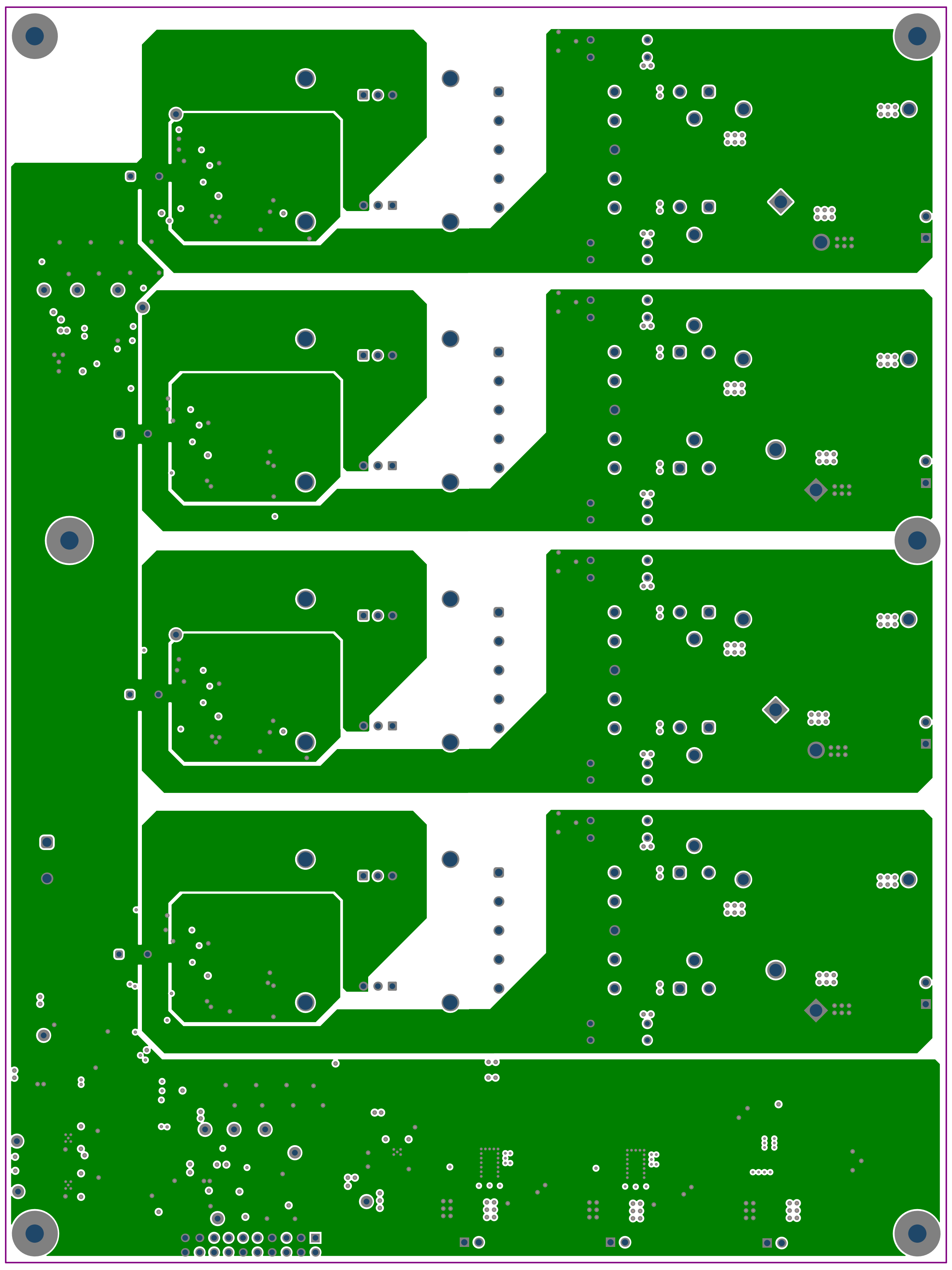
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: TIDA-01352		
PLOT NAME = TOP PASTE	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



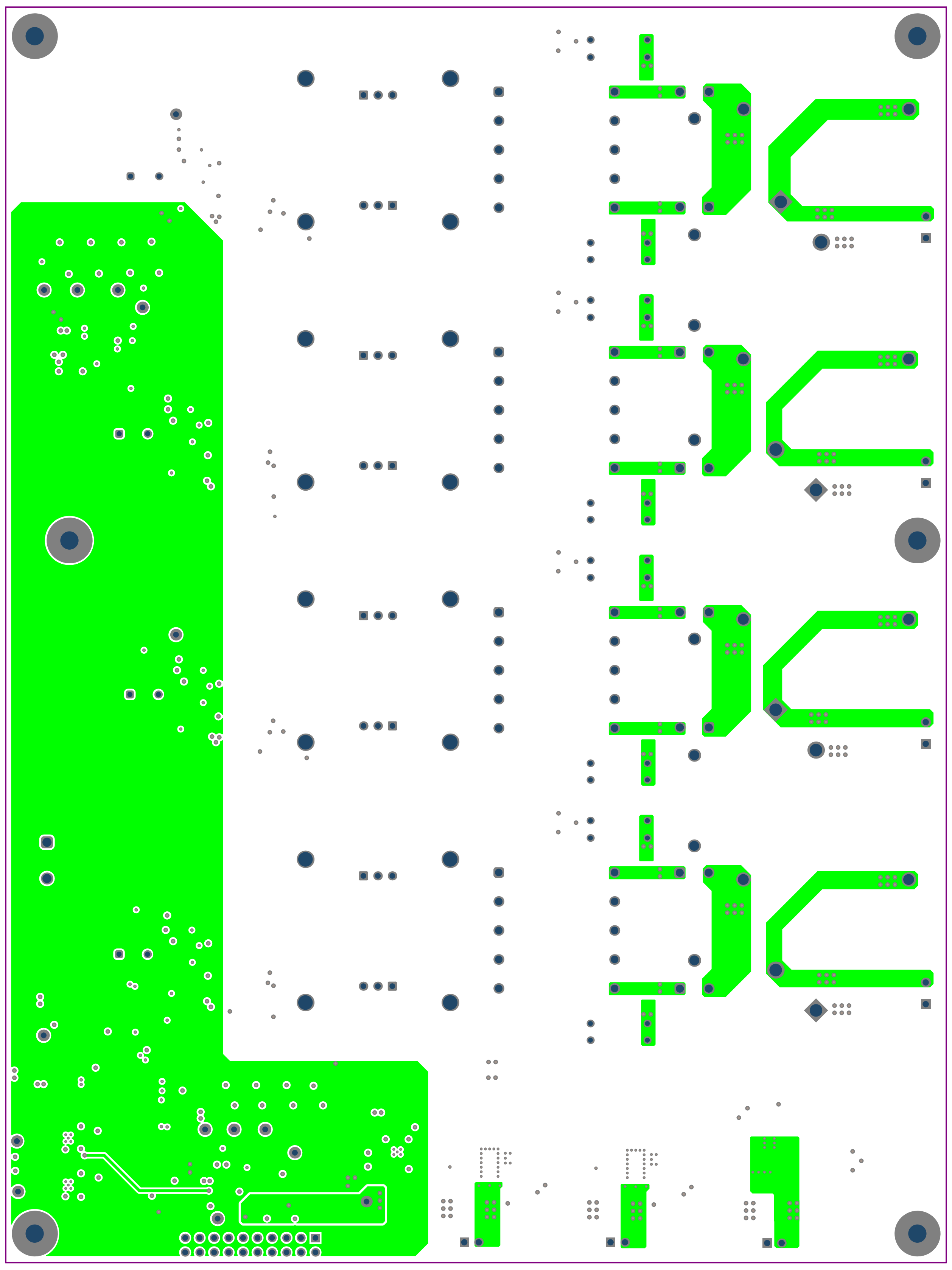
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01352		
PLOT NAME = Top Solder Mask	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



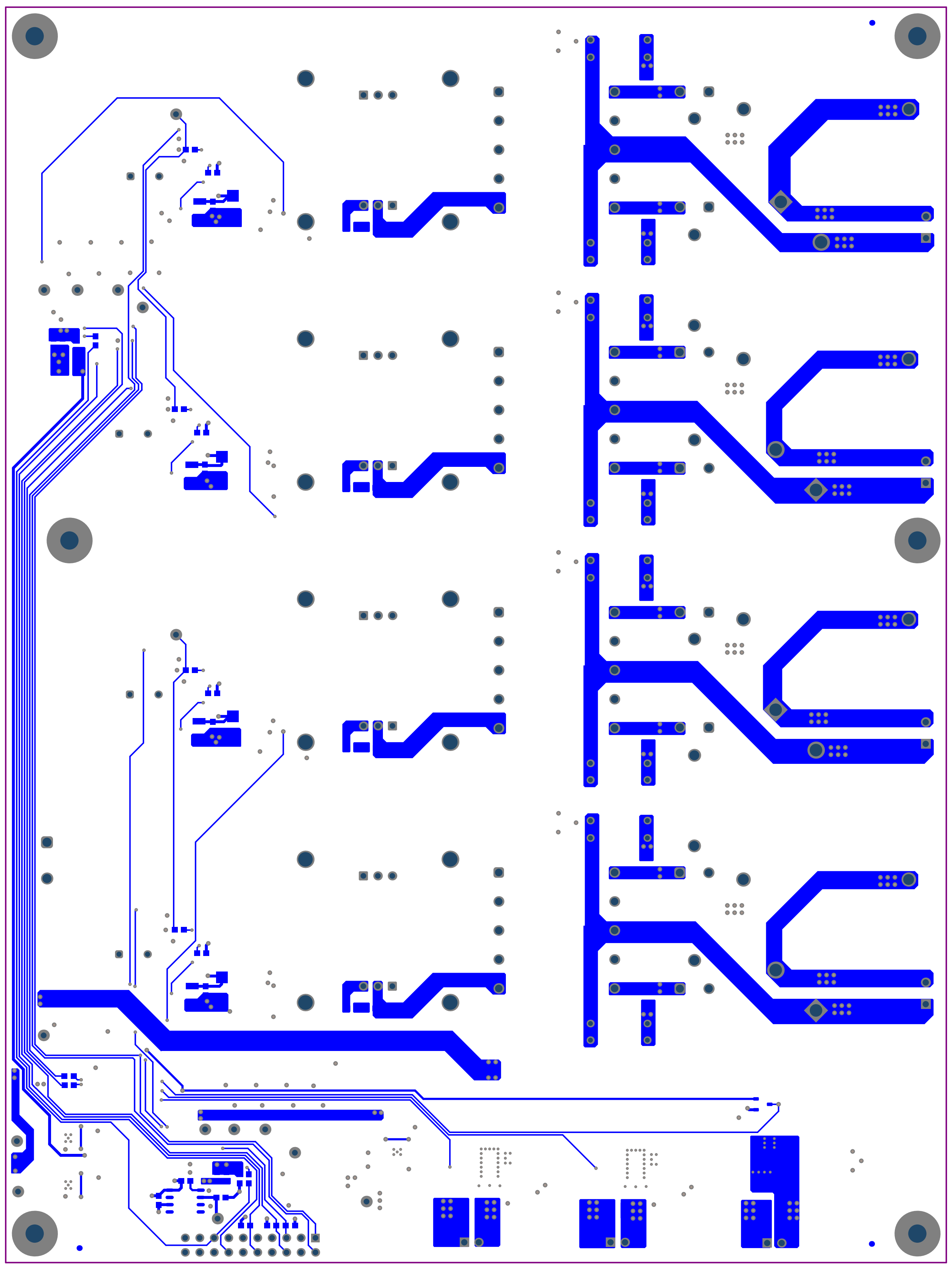
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01352		
PLOT NAME = Top Layer	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



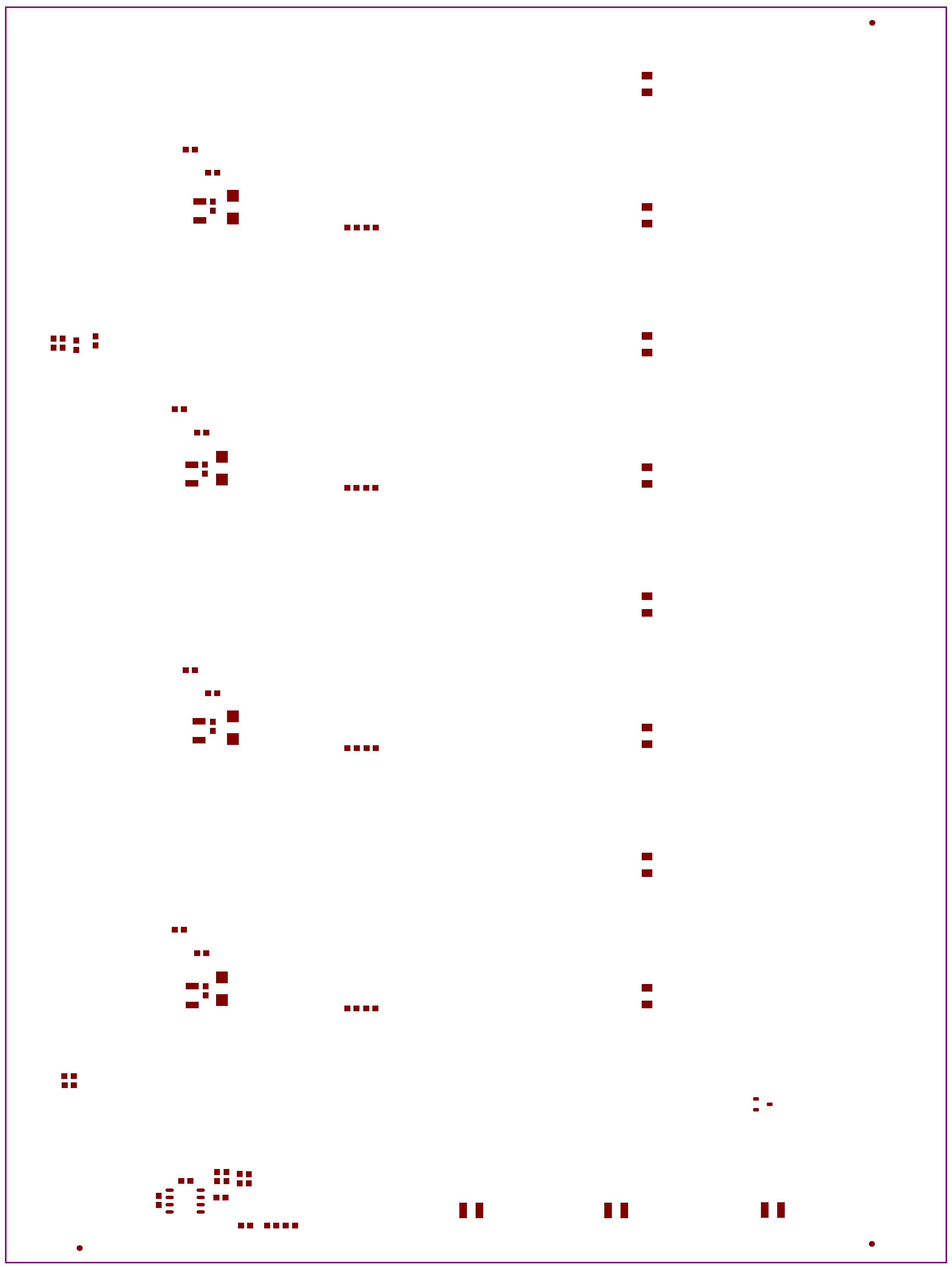
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = GND Layer	TID #: TIDA-01352		
PLOT NAME = GND	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



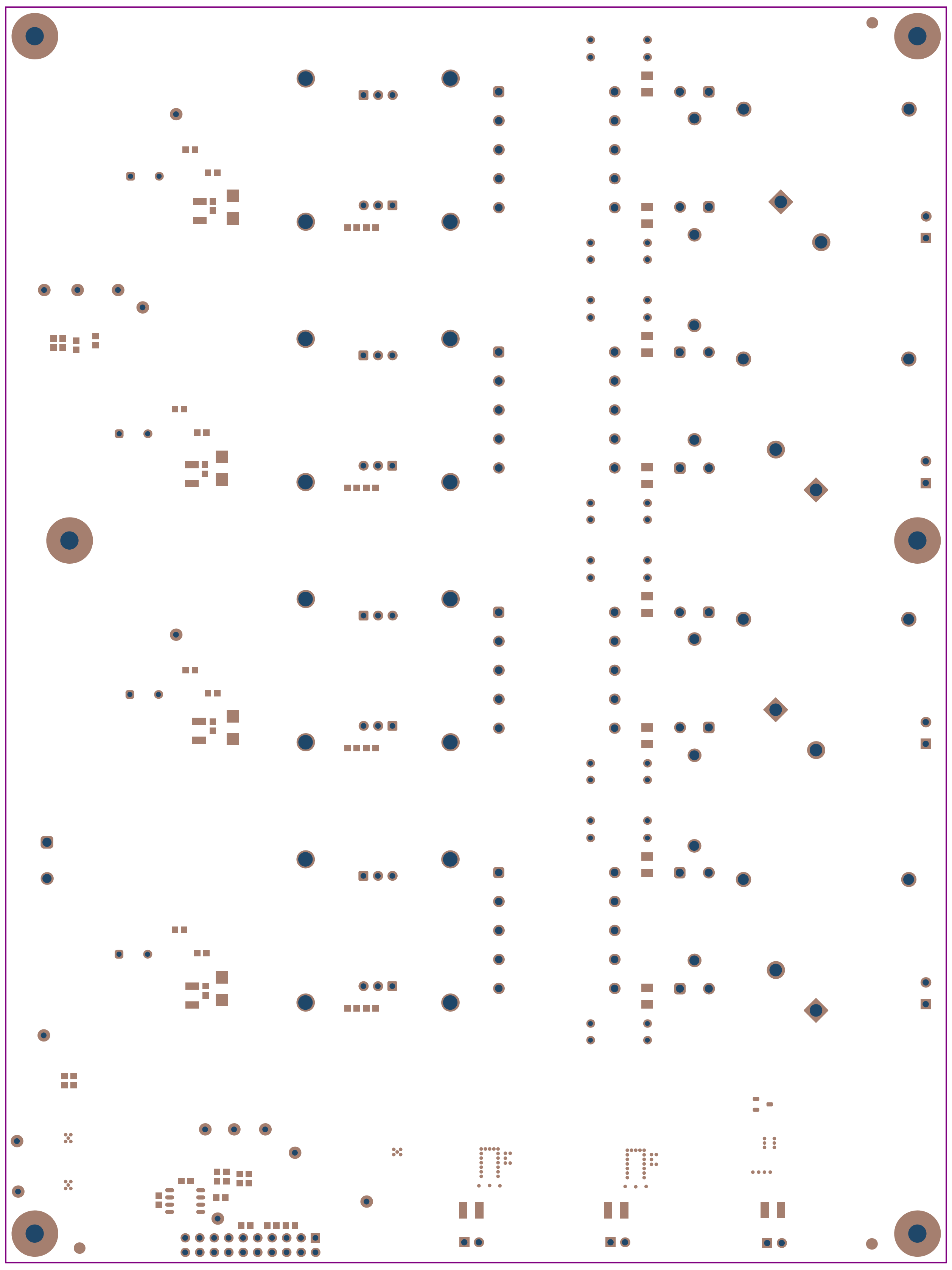
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = PWR Layer	TID #: TIDA-01352		
PLOT NAME = PWR	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01352		
PLOT NAME = Bottom Layer	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS

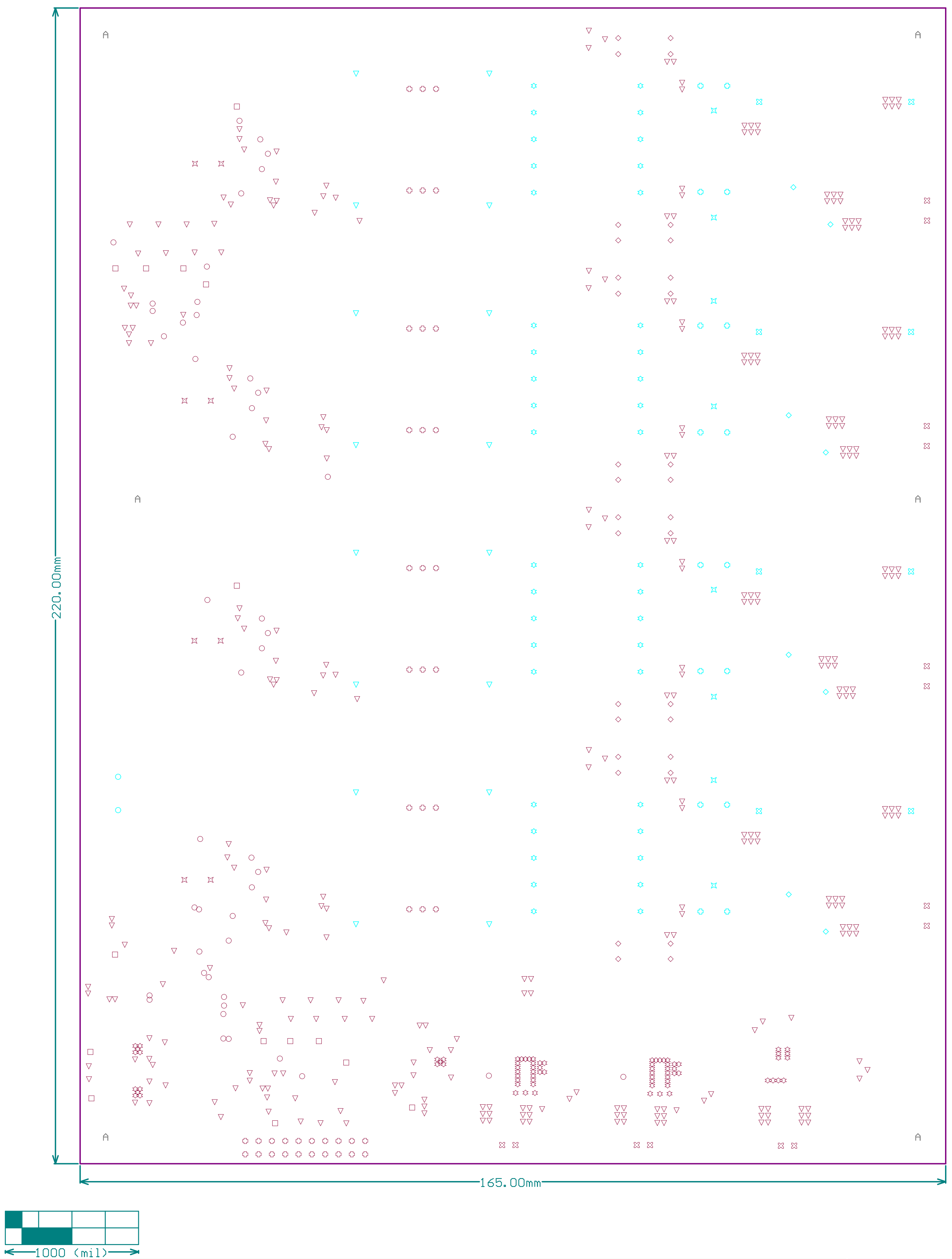


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: TIDA-01352		
PLOT NAME = BOTTOM PASTE	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01352		
PLOT NAME = Bottom Solder Mask	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01352		
PLOT NAME = Bottom Overlay	GENERATED : 19-06-2017 14:45:40		TEXAS INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
✡	75	7.874mil (0.2mm)	PTH	Round
○	46	12mil (0.305mm)	PTH	Round
▽	325	16mil (0.406mm)	PTH	Round
◇	32	33.465mil (0.85mm)	PTH	Round
⌘	8	35.433mil (0.9mm)	PTH	Round
✙	44	39.37mil (1mm)	PTH	Round
□	15	40mil (1.016mm)	PTH	Round
⌧	14	43.307mil (1.1mm)	PTH	Round
✡	40	51.968mil (1.32mm)	PTH	Round
✙	16	55.118mil (1.4mm)	PTH	Round
○	2	62.992mil (1.6mm)	PTH	Round
⌘	8	68.11mil (1.73mm)	PTH	Round
⌧	8	74.803mil (1.9mm)	PTH	Round
◇	8	86.614mil (2.2mm)	PTH	Round
▽	16	100.394mil (2.55mm)	PTH	Round
A	6	125.984mil (3.2mm)	PTH	Round
	663 Total			

DRILL TOLERANCE
FOR PTH +/- 3MIL
7.874mil drill:+0/-7.874mil
12mil drill:+0/-12mil
16mil drill:+0/-16mil

NOTE : Except 7.874 mil vias , all other vias are tented.

Layer Stack Up Detail for: TIDA-01352-E2

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR4-High Tg
GND	(.G1)	1.4mil	FR4-High Tg
PWR	(.G2)	1.4mil	FR4-High Tg
Bottom Layer	(.GBL)	1.4mil	FR4-High Tg
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

165 mm X 220 mm

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 3.937 MIL
MIN. VIA PAD SIZE: 19.695 MIL

MINIMUM ANNULAR RING 5.9055 MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 63 MIL (1.6mm) +/-10% ☐ OTHER ______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______

COPPER THICKNESS (FINISHED):
OUTER: ☒ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☐ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ______
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS
TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES ☒ NO ☐
MICROSECTION: ☐ YES IMPEDANCE CONTROL: YES ☐ NO ☒
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:
Pulser Power Supply

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-01352.PcbDoc

ENGINEER:
Sanjay Pithadia

LAYOUT BY:
Avinash N

SCALE: 1.00

ALTIUM DESIGNER VERSION:
16.0.5.271

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01352	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01352		
PLOT NAME = Drill Drawing	GENERATED : 19-06-2017 14:45:41		TEXAS INSTRUMENTS

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